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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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**In re Application of:** Mok et al.

**Docket No.:** NNEX0003

**Serial No.:** 09/980,040

**Art Unit:** 2839

10

**Filed:** 27 December 2001

**Examiner:** Duverne, Jean F.

**Title:** Construction Structures and Manufacturing Processes for Integrated Circuit Wafer Probe Card Assemblies

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14 January 2004

Assistant Commissioner for Patents

Mail Stop Non Fee Amendment

P.O. Box 1450

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Alexandria, VA 22313-1450

**AMENDMENT IN RESPONSE TO OFFICE ACTION**

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Sir:

This is in response to the Office Action filed by the Examiner, which was mailed to Applicant on 15 October 2003, for the above-identified patent application. Applicant considers this document to be filed in a timely manner.

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01/14/2004 WED 15:10 FAX 650 474 8401 GLENN PATENT GROUP

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Certificate of Transmission Under 37 C.F.R. §1.8			
I hereby certify that this document and the documents referred to herein as attached are being transmitted via facsimile to the United States Patent and Trademark Office, Attn: Jean F. Duverne to facsimile number (703) 872-9306 on the below indicated date of deposit.			
Date of Deposit:	1/14/2004	Name of Person Making the Deposit:	Rhonda Dunn
		Signature of the Person Making the Deposit:	<i>Rhonda Dunn</i>

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January 14, 2004

Re: **Non-Final Amendment**

To: United States Patent and Trademark Office  
Fax: (703) 872-9306  
Attention: Jean F. Duverne, Art Unit 2839

Pages (including coversheet): 22

***Attached to this facsimile coversheet please find the following documents:***

- Amendment (21 pages)